



FG676 - 63/37 (Sn/Pb) Solder Balls
 FGG676 - Sn/Ag/Cu Solder Balls

SYMBOL	MILLIMETERS		
	MIN.	NOM.	MAX.
A	∇	2.25	2.60
A ₁	0.40	0.50	0.60
D/E	27.00 BSC		
D ₁ /E ₁	25.00 REF		
e	1.00 BSC		
ϕ_b	0.50	0.60	0.70
aaa	∇	∇	0.20
ccc	∇	∇	0.35
ddd	∇	∇	0.30
eee	∇	∇	0.10
M	26		

NOTES:

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994
2. SYMBOL 'M' IS THE BALL MATRIX SIZE.
3. CONFORMS TO JEDEC MS-034-AAL-1

676-BALL FINE-PITCH BGA, 1.00MM PITCH (FG676/FGG676)